

LP4411ET1G

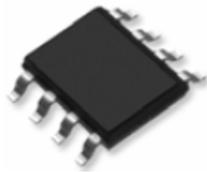
P-Channel Enhancement Mode Field Effect Transistor Features

$$V_{DS} (V) = -30V$$

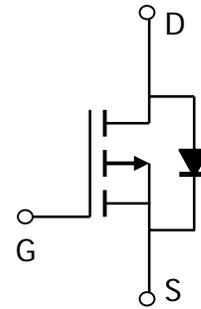
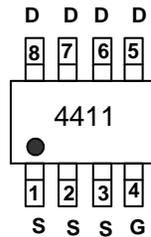
$$I_D = -8 A (V_{GS} = -10V)$$

$$R_{DS(ON)} < 32m\Omega (V_{GS} = -10V)$$

$$R_{DS(ON)} < 55m\Omega (V_{GS} = -4.5V)$$



SOP-8 top view



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted			
Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^A	I_D	$T_A=25^\circ\text{C}$	-8
		$T_A=70^\circ\text{C}$	-6.6
Pulsed Drain Current ^B	I_{DM}	-40	A
Power Dissipation ^A	P_D	$T_A=25^\circ\text{C}$	3
		$T_A=70^\circ\text{C}$	2.1
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics					
Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$t \leq 10s$	$R_{\theta JA}$	24	40	$^\circ\text{C/W}$
Maximum Junction-to-Ambient ^A	Steady-State		54	75	$^\circ\text{C/W}$
Maximum Junction-to-Lead ^C	Steady-State	$R_{\theta JL}$	21	30	$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}$, $V_{GS}=0\text{V}$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-24\text{V}$, $V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			-1 -5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-1.2	-2	-2.4	V
$I_{D(ON)}$	On state drain current	$V_{GS}=-10\text{V}$, $V_{DS}=-5\text{V}$	-40			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$, $I_D=-8\text{A}$ $T_J=125^\circ\text{C}$		24.5 33	32	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-5\text{A}$		41	55	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}$, $I_D=-8\text{A}$		14.5		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}$, $V_{GS}=0\text{V}$		-0.76	-1	V
I_S	Maximum Body-Diode Continuous Current				-4.2	A
DYNAMIC PARAMETERS						
C_{ISS}	Input Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=-15\text{V}$, $f=1\text{MHz}$		920	1120	pF
C_{OSS}	Output Capacitance		190		pF	
C_{RSS}	Reverse Transfer Capacitance		122		pF	
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1\text{MHz}$		3.6	5	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge (10V)	$V_{GS}=-10\text{V}$, $V_{DS}=-15\text{V}$, $I_D=-8\text{A}$		18.4	23	nC
$Q_g(4.5\text{V})$	Total Gate Charge (4.5V)		9.3	11.5	nC	
Q_{gs}	Gate Source Charge		2.7		nC	
Q_{gd}	Gate Drain Charge		4.9		nC	
$t_{D(on)}$	Turn-On DelayTime	$V_{GS}=-10\text{V}$, $V_{DS}=-15\text{V}$, $R_L=1.8\Omega$, $R_{GEN}=3\Omega$		7.1		ns
t_r	Turn-On Rise Time		3.4		ns	
$t_{D(off)}$	Turn-Off DelayTime		18.9		ns	
t_f	Turn-Off Fall Time		8.4		ns	
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-8\text{A}$, $di/dt=100\text{A}/\mu\text{s}$		21.5	27	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-8\text{A}$, $di/dt=100\text{A}/\mu\text{s}$		12.5		nC

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

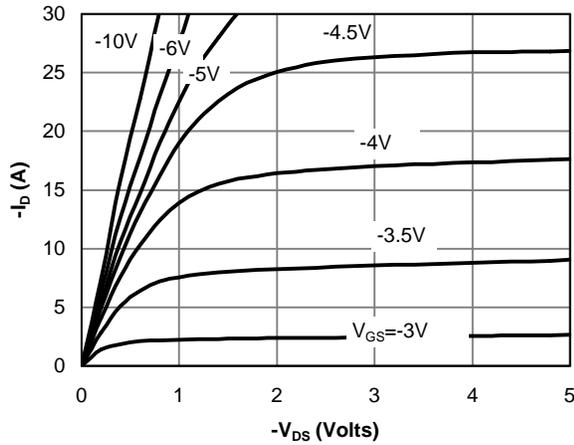


Fig 1: On-Region Characteristics

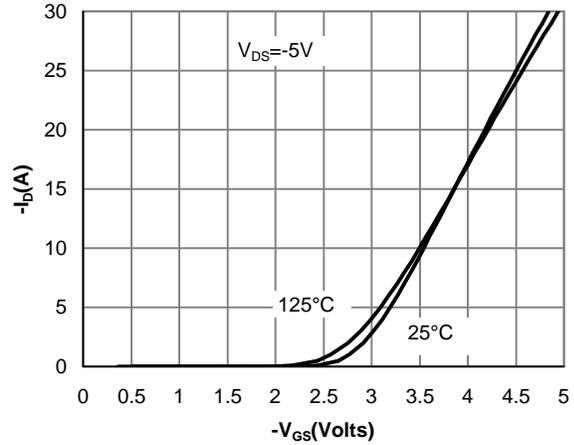


Figure 2: Transfer Characteristics

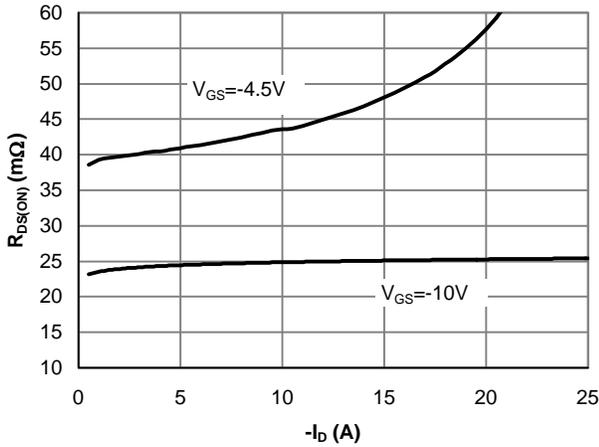


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

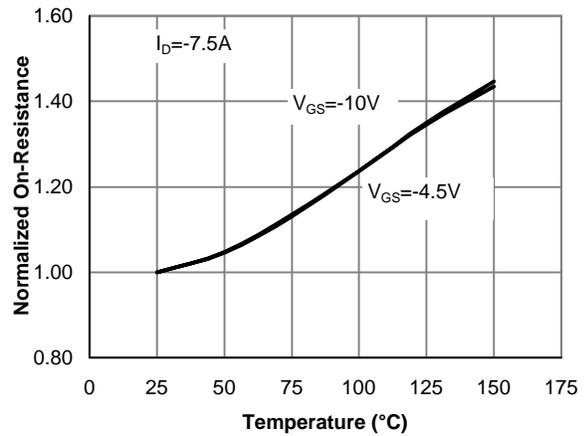


Figure 4: On-Resistance vs. Junction Temperature

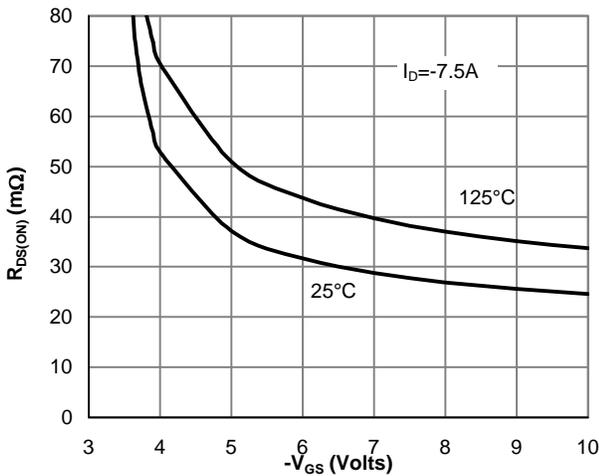


Figure 5: On-Resistance vs. Gate-Source Voltage

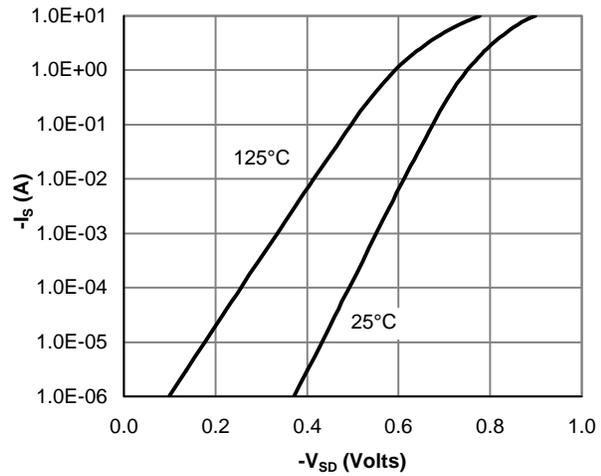


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

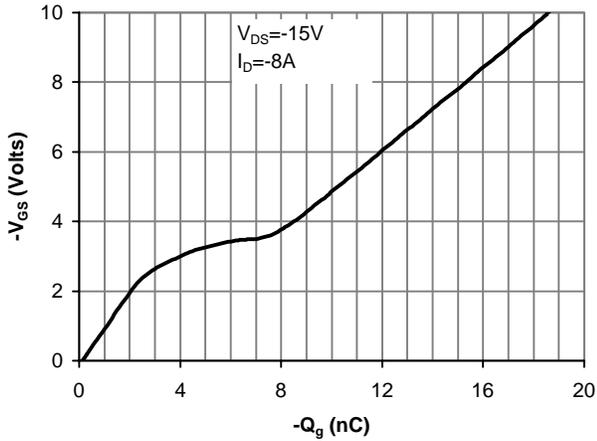


Figure 7: Gate-Charge Characteristics

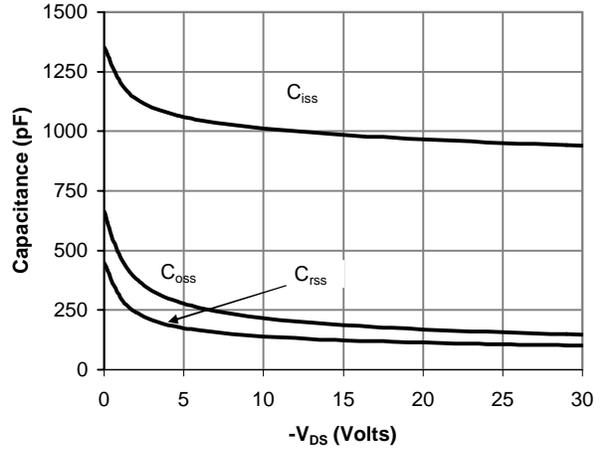


Figure 8: Capacitance Characteristics

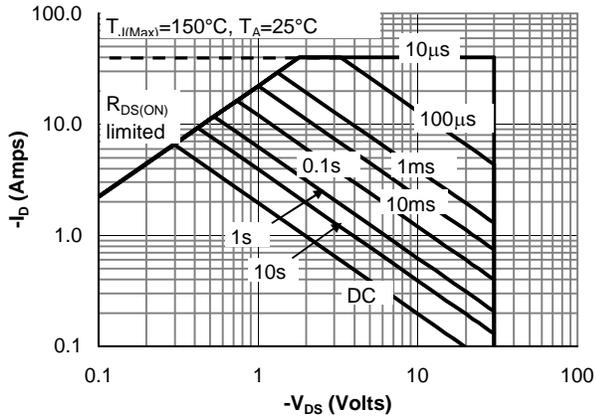


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

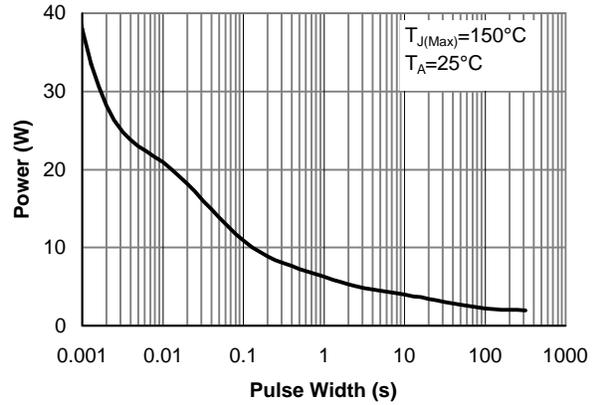


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

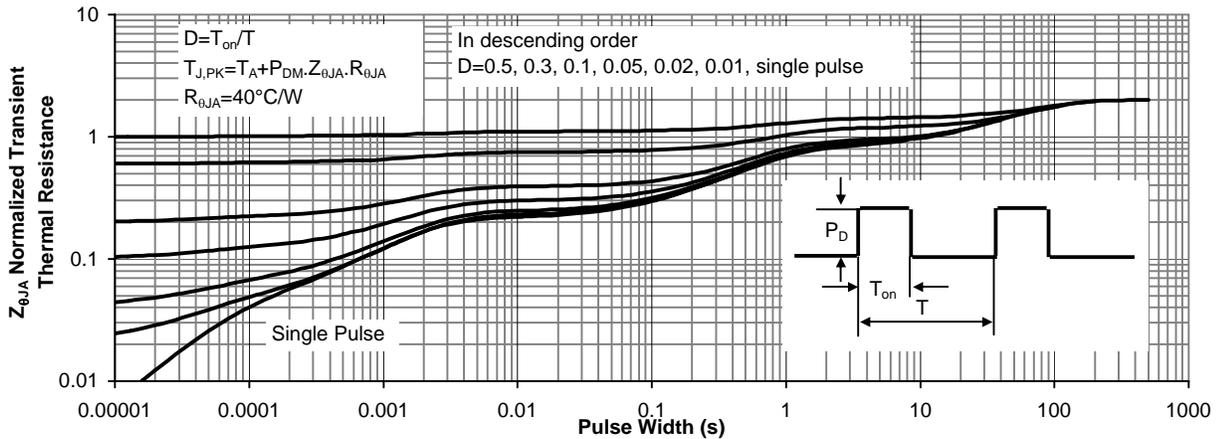


Figure 11: Normalized Maximum Transient Thermal Impedance

SOP-8
